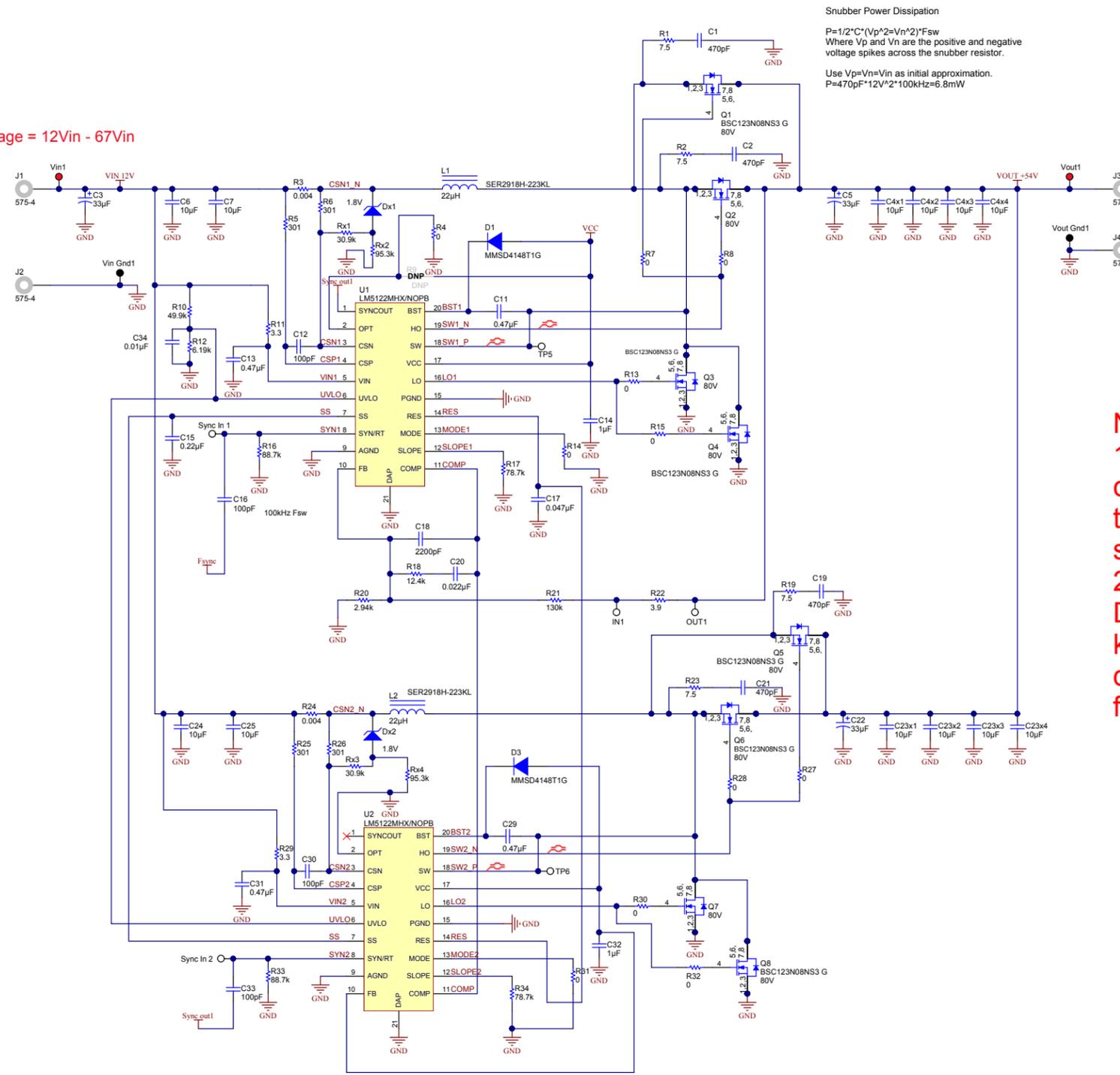


Input Voltage = 12Vin - 67Vin



Snubber Power Dissipation
 $P = 1/2 \cdot C \cdot (V_p^2 - V_n^2) \cdot F_{sw}$
 Where V_p and V_n are the positive and negative voltage spikes across the snubber resistor.
 Use $V_p = V_n = V_{in}$ as initial approximation.
 $P = 470pF \cdot 12V^2 \cdot 100kHz = 6.8mW$

54Vout @ 4.8A

Note:
 1. C4x and C23x are ceramic caps stacked on top of each other on one single footprint.
 2. Rx1, Rx2, Rx3, Rx4, Dx1 and Dx2 are kludged on the board, don't have dedicated footprint on the PCB.

Orderable: N/A	Designed for: Public Release	Mod. Date: 1/15/2016
TID #: PMP7979	Project Title: LMS122 Dual Phase Boost	
Number: PMP7979	Rev: B	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet 1 of 2
Drawn By: Xinyu Dai	File: PMP7979 REV B SchDoc	Size: C
Engineer: Xinyu Dai	Contact: http://www.ti.com/support	

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A

A



PCB: PMP7850 REVB
PMP7850 REVB

PCB LOGO
Texas Instruments

PCB LOGO
Pb-Free Symbol

B

B

Label Table	
Variant	Label Text
001	

C

C

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

D

D

Orderable: N/A	Designed for: Public Release	Mod. Date: 12/8/2015	 http://www.ti.com © Texas Instruments 2015
TID #: PMP7979	Project Title: LM5122 Dual Phase Boost		
Number: PMP7979	Rev: B	Sheet Title:	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 2	
Drawn By: Xinyu Dai	File: PMP7979_Hardware_REVB.SchDoc	Size: B	
Engineer: Xinyu Dai	Contact: http://www.ti.com/support		

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